PRODUCT ADVANTAGE

Eliminate cleaning process for ball bumping
Enhances solder joint strength 5-10X
Eliminates underfill
Excellent process compatibility
High reliability
100% reworkable

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OUR THREE PILLARS

1. EXCEEDING PERFORMANCE SPECIFICATIONS
2. MAXIMIZING PRODUCTIVITY
3. LOWERING PROCESS COST

BP 256
BALL ATTACH ADHESIVE OVERVIEW

Preferred by global leaders in the electronics manufacturing industry
YINCAE® BP 256 Ball Attach Adhesives

Process flow for BP 256:
1. Apply BP 256 onto pads
2. Place solder balls
3. Send through reflow

Availability:
BP 256 - R
Red, used for printing applications

BP 256 - B
Black, used for printing applications

BP 256 - T
Clear, used for pin transfer applications

The YINCAE® BP 256 products are a series of lead-free (SAC alloys) ball bumping adhesives that are designed to enhance solder joint reliability and eliminate cleaning processes for ball bumping procedures on CSP, BGA, flip chip, and PoP applications.

BP 256 is designed to eliminate underfilling processes during SMT assembly and thus reduces cost and increases throughput.

BP 256 has demonstrated excellent drop and thermal cycling performance as well as a high and consistent shear strength.

Contact YINCAE at info@yincae.com for detailed specifications & customization for your specific product requirements.